

Special Issue

Advanced MEMS and Optical System Assembly and Integration

Message from the Guest Editors

The research and development of advanced MEMS and optical systems has attracted attention from both academia and industry. They are tremendously valuable for enabling new applications including augmented reality/mixed reality (AR/MR), autonomous driving systems (ADS), unmanned aerial vehicles (UAV), optical image stabilization (OIS) and robotic vision. The whole system requires the integration of multiple components, such as MEMS scanning mirrors, laser diodes, micro-LED arrays, waveguides, image sensors, and time-of-flight (ToF) sensors. There is a strong need to develop advanced assembly and packaging processes for the individual component or large component arrays. Meanwhile, new ideas of system-level co-design and optical mechanical architecture are necessary to improve performance, miniaturization, yield, and reliability. In this Special Issue, we would like to invite you to contribute research papers, communications, and review articles related to advanced MEMS and optical system assembly and integration architectures, designs, processes, testing approaches and simulations.

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Deadline for manuscript submissions

closed (31 March 2022)



Micromachines

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Impact Factor 3.0
CiteScore 6.0
Indexed in PubMed



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Editor-in-Chief

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